- **Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

## description

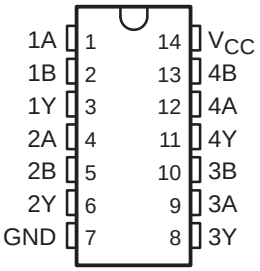
These devices contain four independent 2-input positive-NAND buffers with open-collector outputs. They perform the Boolean functions $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic. The open-collector outputs require pullup resistors to perform correctly. These outputs may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices often are used to generate higher $V_{OH}$ levels.

The SN54ALS38B is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS38B is characterized for operation from 0°C to 70°C.

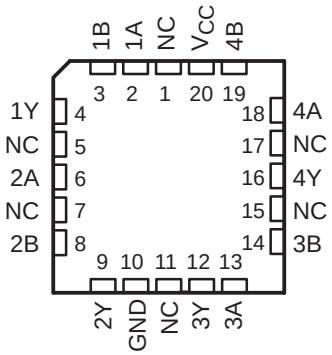
**FUNCTION TABLE**
**(each gate)**

| INPUTS | | OUTPUT |
|---|---|---|
| A | B | Y |
| H | H | L |
| L | X | H |
| X | L | H |

**SN54ALS38B . . . J PACKAGE**
**SN74ALS38B . . . D OR N PACKAGE**
**(TOP VIEW)**

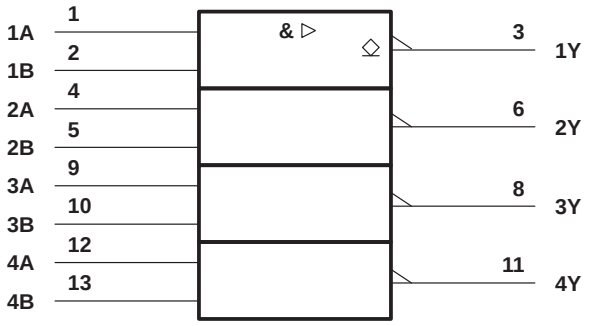



**SN54ALS38B . . . FK PACKAGE**
**(TOP VIEW)**




NC – No internal connection

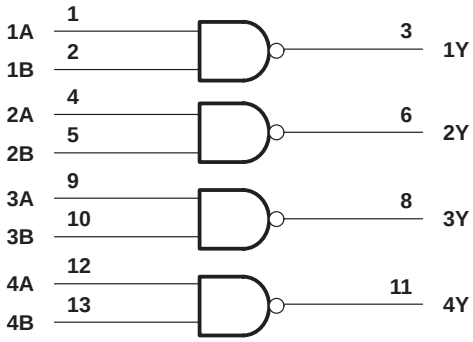
## logic symbol†




† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

## logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$ . . . . . 7 V
Input voltage, $V_I$ . . . . . 7 V
Operating free-air temperature range, $T_A$: SN54ALS38B . . . . . –55°C to 125°C
SN74ALS38B . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

| | | SN54ALS38B | | | SN74ALS38B | | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| $V_{IH}$ | High-level input voltage | 2 | | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage | | | 0.7 | | | 0.8 | V |
| $V_{OH}$ | High-level output voltage | | | 5.5 | | | 5.5 | V |
| $I_{OL}$ | Low-level output current | | | 12 | | | 24 | mA |
| $T_A$ | Operating free-air temperature | –55 | | 125 | 0 | | 70 | °C |

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | SN54ALS38B | | | SN74ALS38B | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | |
| $V_{IK}$ | $V_{CC}$ = 4.5 V, | $I_I$ = –18 mA | | | –1.5 | | | –1.5 | V |
| $V_{OL}$ | $V_{CC}$ = 4.5 V | $I_{OL}$ = 12 mA | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| | | $I_{OL}$ = 24 mA | | | | | 0.35 | 0.5 | |
| $I_I$ | $V_{CC}$ = 5.5 V, | $V_I$ = 7 V | | | 0.1 | | | 0.1 | mA |
| $I_{IH}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 2.7 V | | | 20 | | | 20 | µA |
| $I_{IL}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 0.4 V | | | –0.1 | | | –0.1 | mA |
| $I_{OH}$ | $V_{CC}$ = 4.5 V, | $V_{OH}$ = 5.5 V | | | 0.1 | | | 0.1 | mA |
| $I_{CCH}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 0 | | 0.86 | 1.6 | | 0.86 | 1.6 | mA |
| $I_{CCL}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 4.5 V | | 4.8 | 7.8 | | 4.8 | 7.8 | mA |

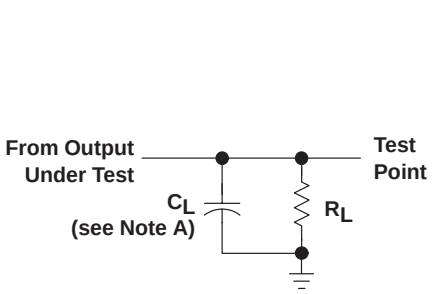
‡ All typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.

### switching characteristics (see Figure 1)

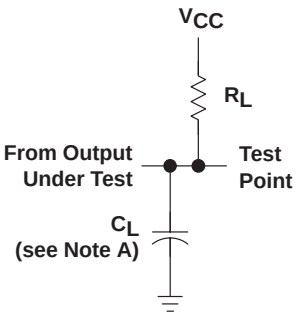
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 500 Ω, $T_A$ = MIN to MAX§ | | | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | SN54ALS38B | | SN74ALS38B | | |
| | | | MIN | MAX | MIN | MAX | |
| $t_{PLH}$ | A or B | Y | 7 | 59 | 10 | 33 | ns |
| $t_{PHL}$ | | | 2 | 20 | 1 | 12 | |

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

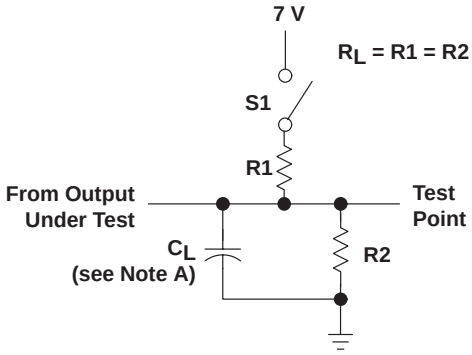
## PARAMETER MEASUREMENT INFORMATION
## SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



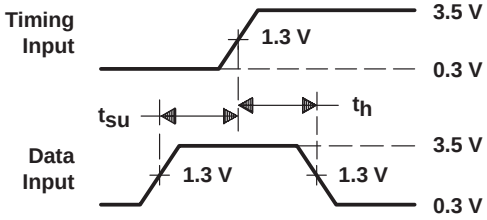

LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS



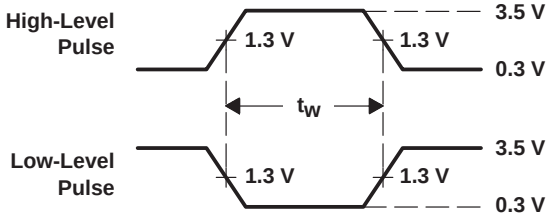

LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



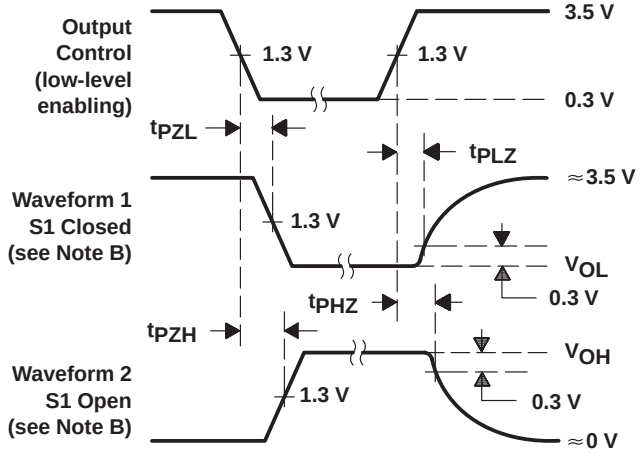

LOAD CIRCUIT
FOR 3-STATE OUTPUTS



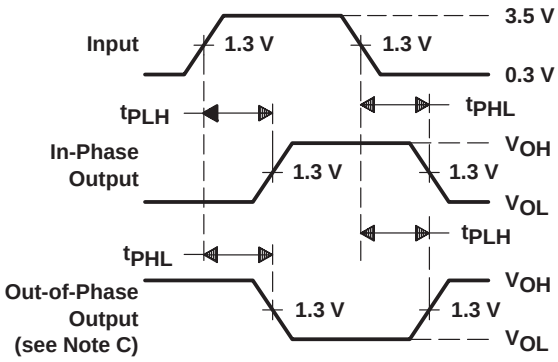

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PULSE DURATIONS




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f$ = 2 ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuits and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 5962-86871012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-86871012A SNJ54ALS38BFK | Samples |
| 5962-8687101CA | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8687101CA SNJ54ALS38BJ | Samples |
| 5962-8687101DA | ACTIVE | CFP | W | 14 | 1 | TBD | Call TI | N / A for Pkg Type | -55 to 125 | 5962-8687101DA SNJ54ALS38BW | Samples |
| SN74ALS38BD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS38B | Samples |
| SN74ALS38BDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS38B | Samples |
| SN74ALS38BDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS38B | Samples |
| SN74ALS38BN | ACTIVE | PDIP | N | 14 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74ALS38BN | Samples |
| SN74ALS38BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS38B | Samples |
| SNJ54ALS38BFK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-86871012A SNJ54ALS38BFK | Samples |
| SNJ54ALS38BJ | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8687101CA SNJ54ALS38BJ | Samples |
| SNJ54ALS38BW | ACTIVE | CFP | W | 14 | 1 | TBD | Call TI | N / A for Pkg Type | -55 to 125 | 5962-8687101DA SNJ54ALS38BW | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



**OTHER QUALIFIED VERSIONS OF SN54ALS38B, SN74ALS38B :**

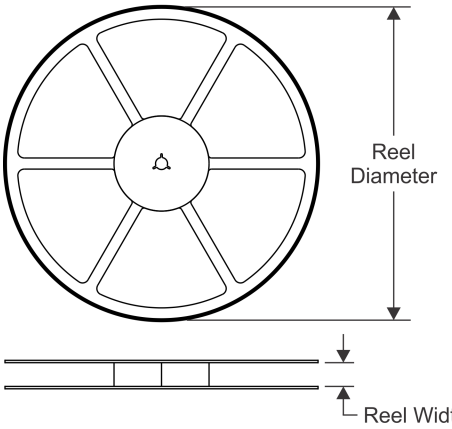
- Catalog: SN74ALS38B
- Military: SN54ALS38B

NOTE: Qualified Version Definitions:

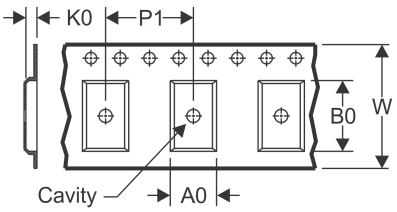
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

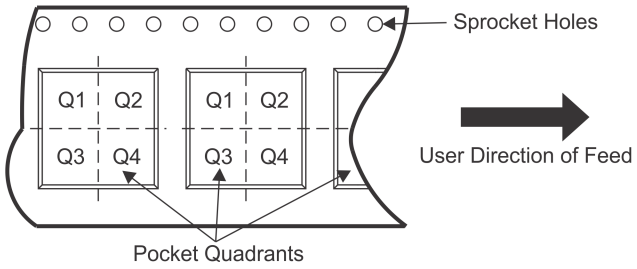



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

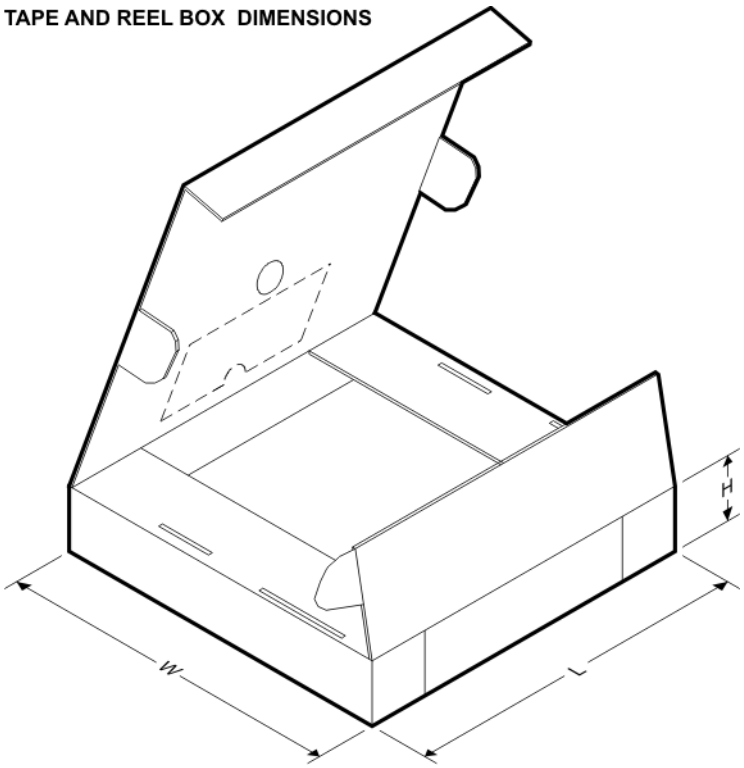
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74ALS38BDR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74ALS38BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS

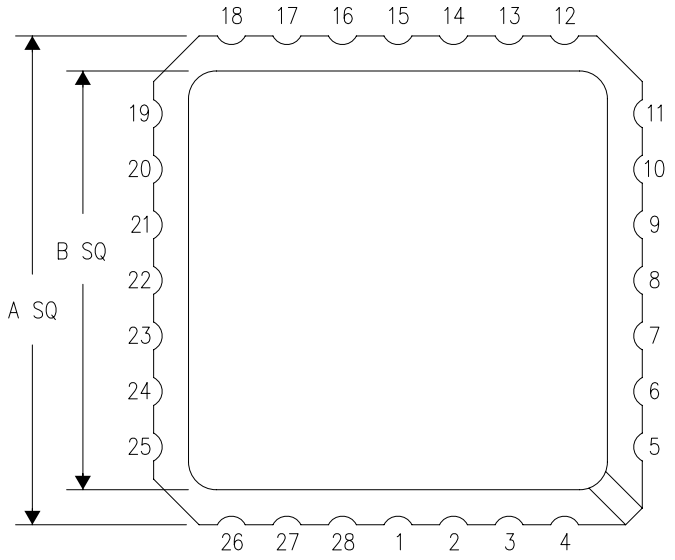



*All dimensions are nominal

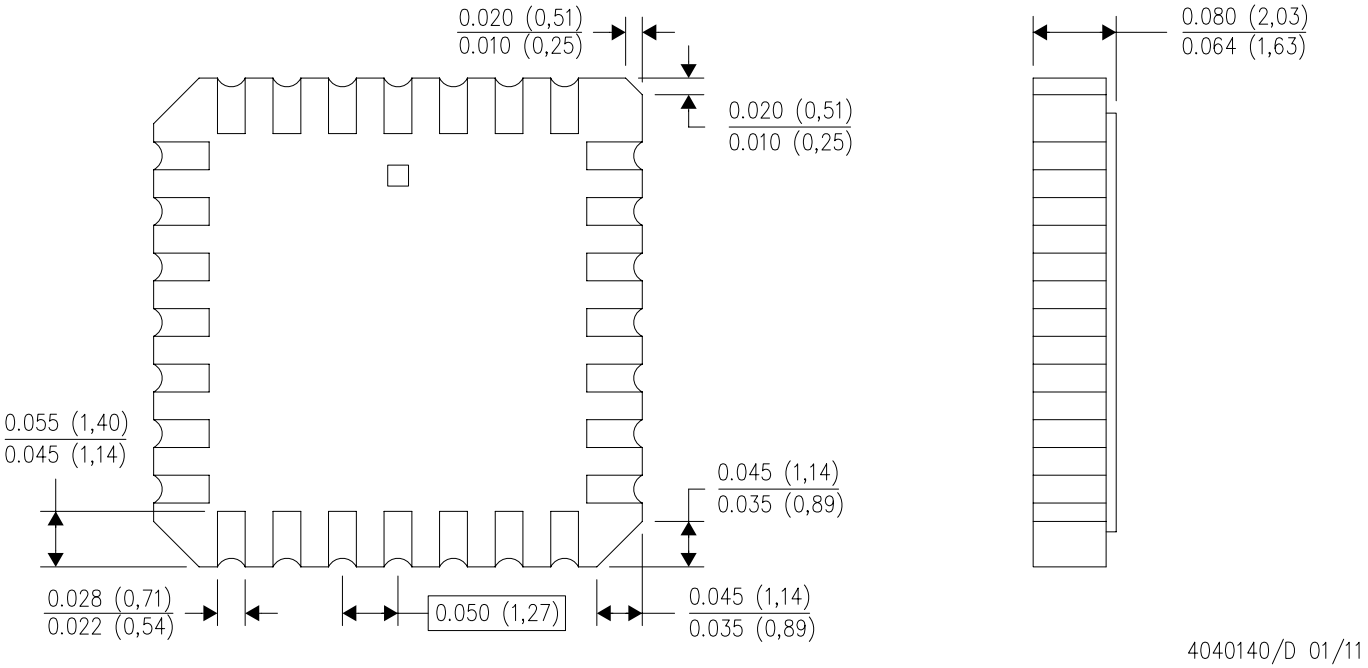
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74ALS38BDR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74ALS38BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN




| NO. OF TERMINALS ** | A | | B | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



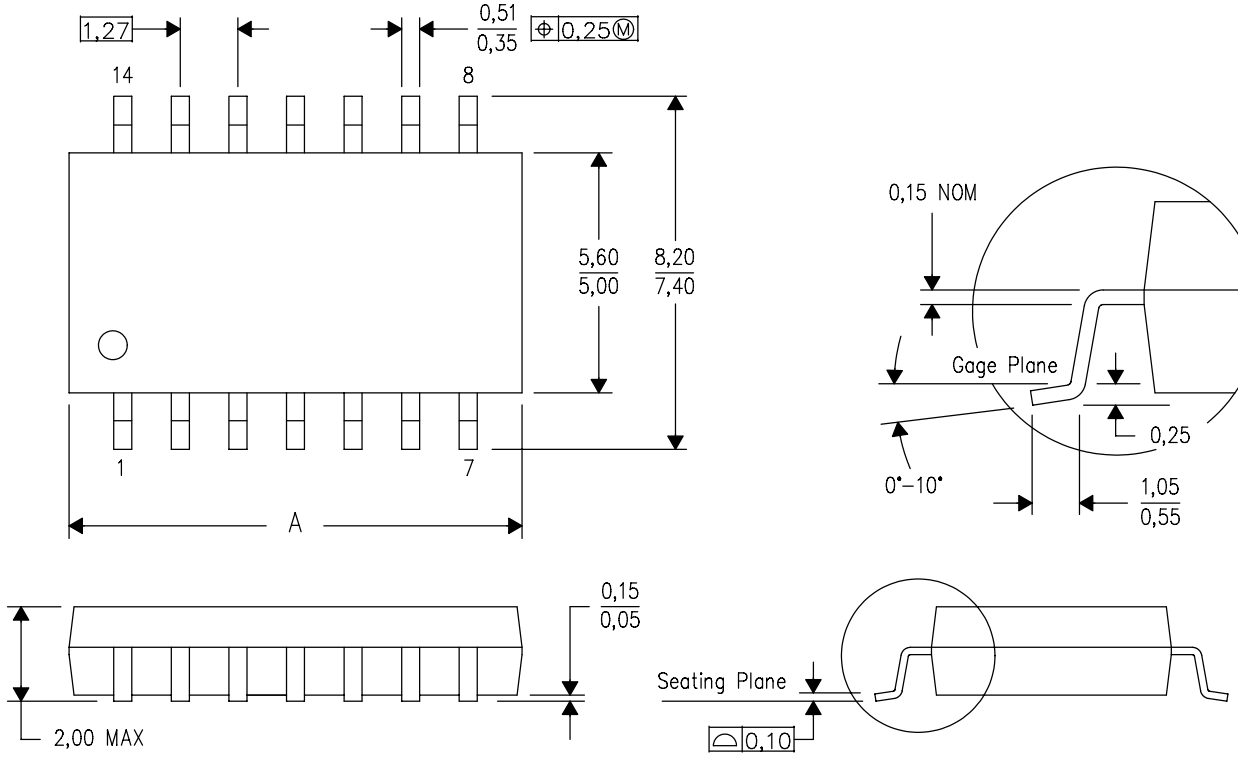

4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

## MECHANICAL DATA

**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**

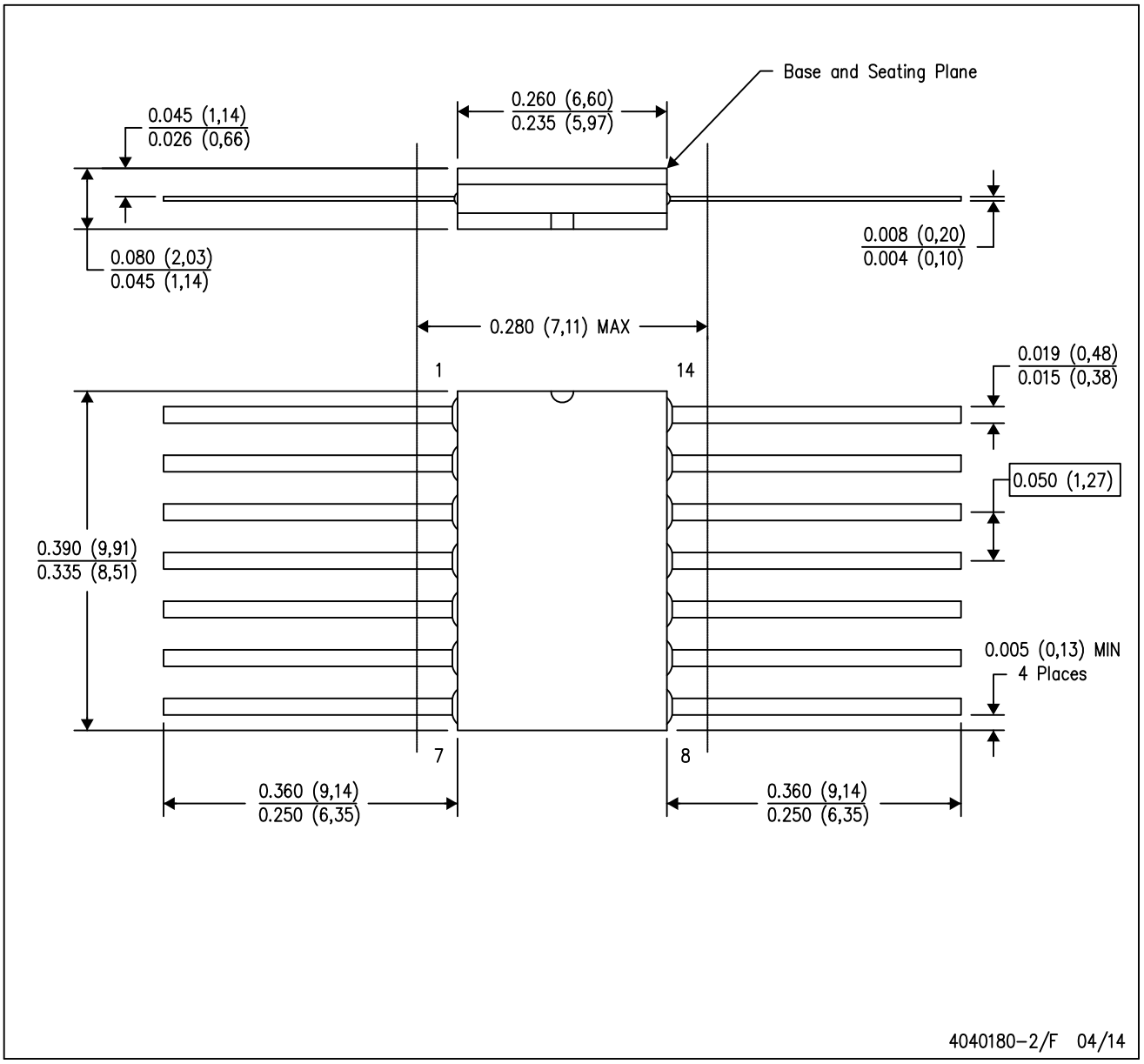



| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK

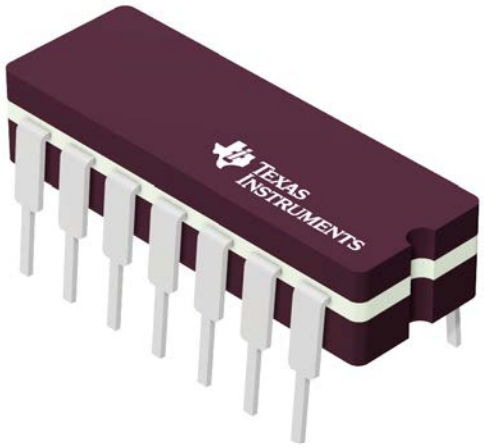



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

# GENERIC PACKAGE VIEW

## J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE




Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

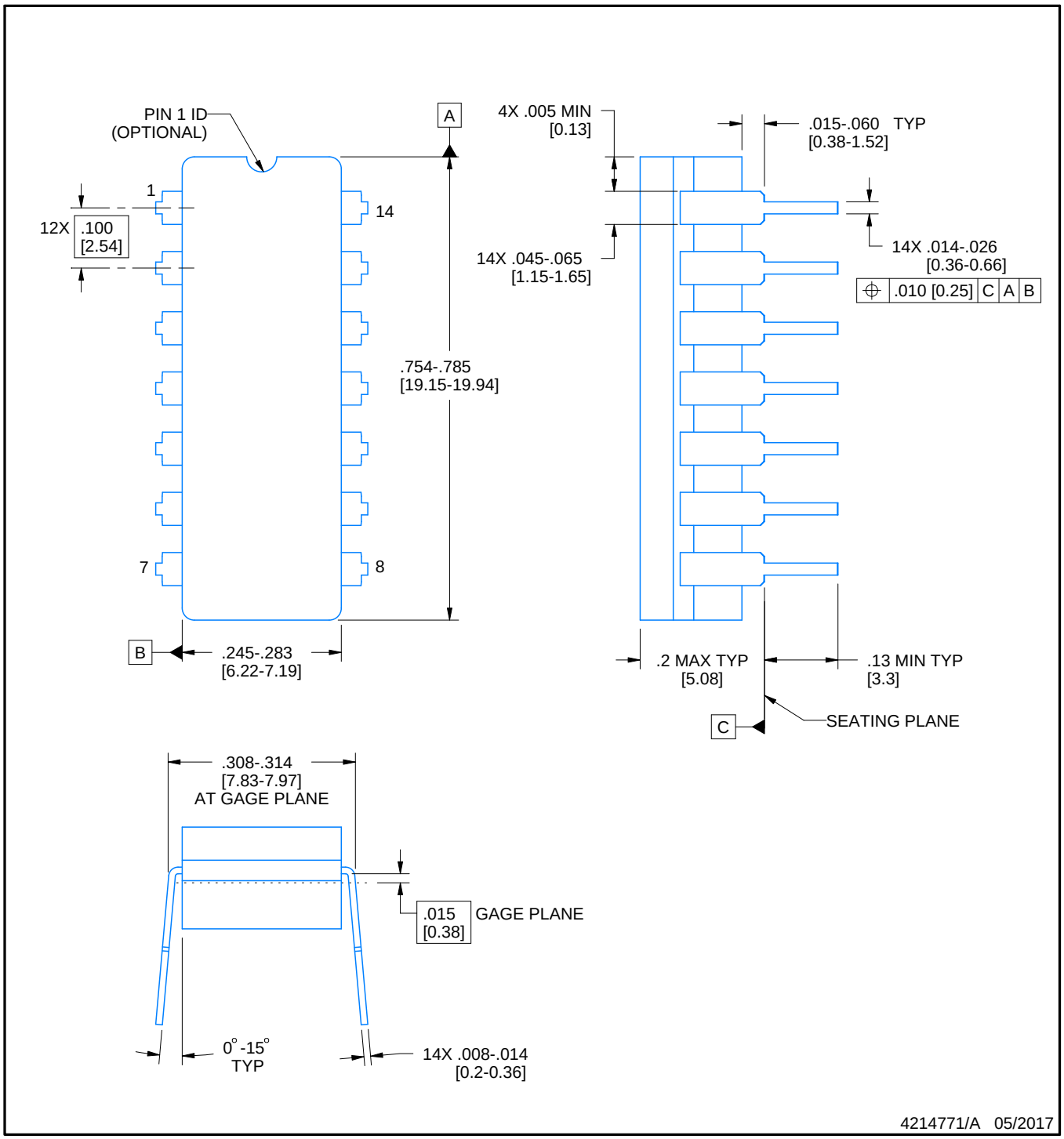
4040083-5/G

# PACKAGE OUTLINE

## J0014A

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE




NOTES:

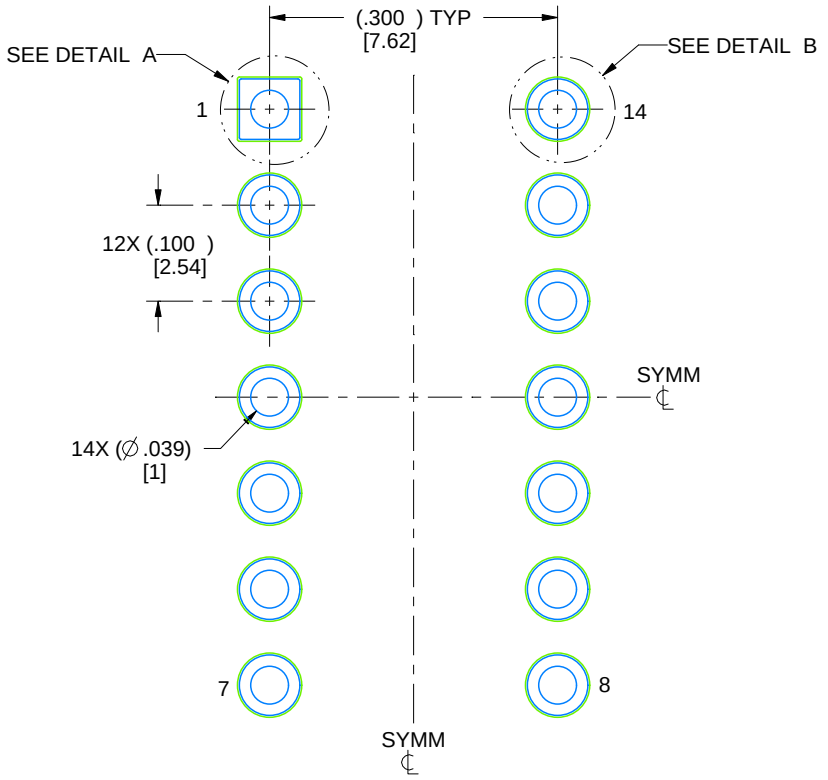
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

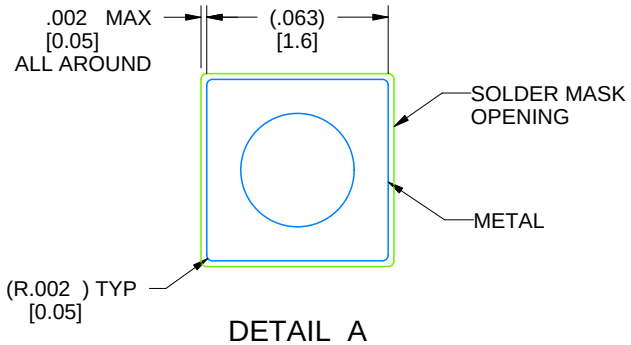
## J0014A

## CDIP - 5.08 mm max height

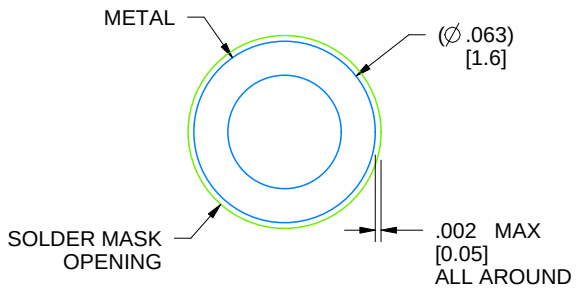
CERAMIC DUAL IN LINE PACKAGE




LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



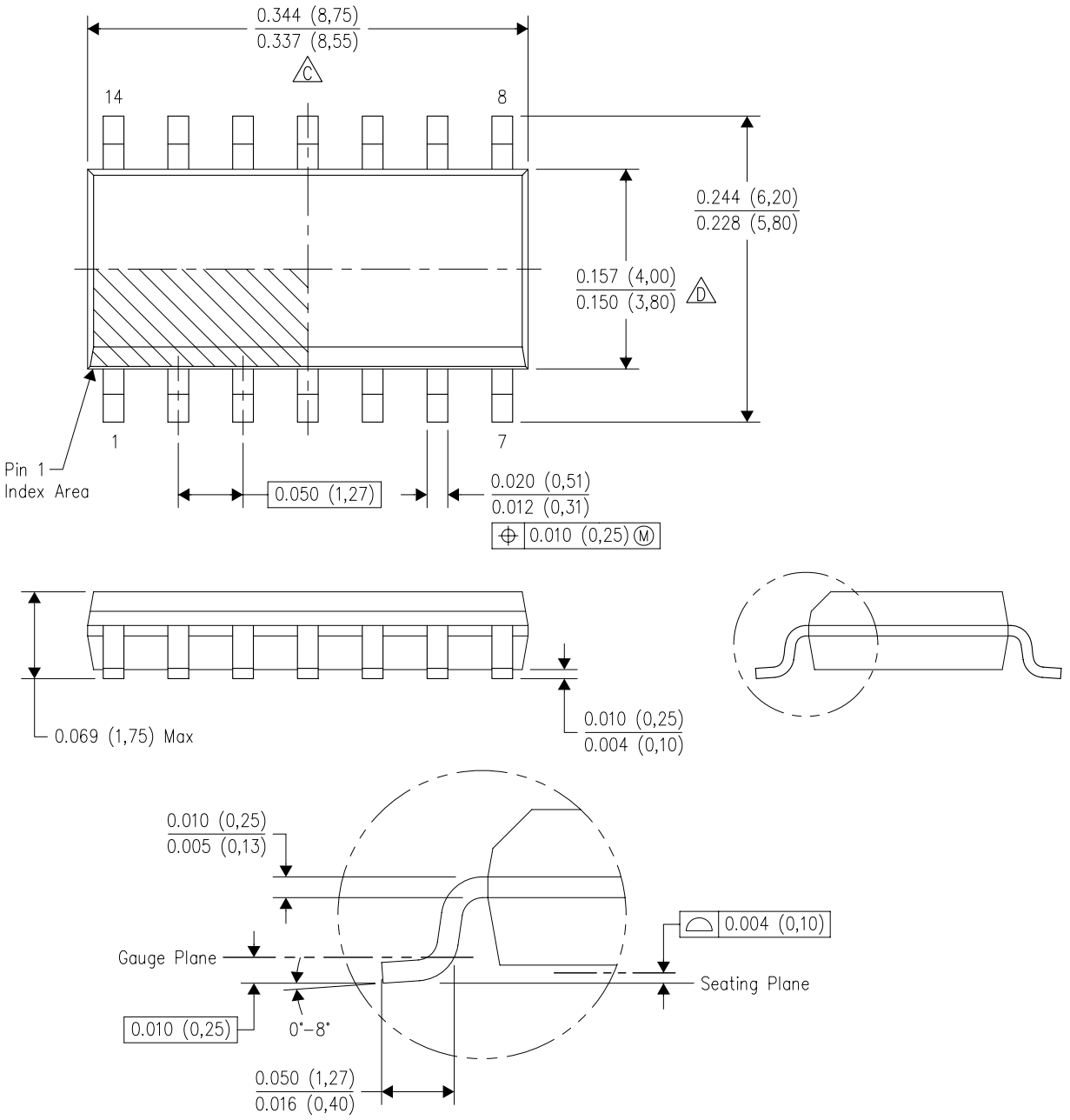

DETAIL A
SCALE: 15X




DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

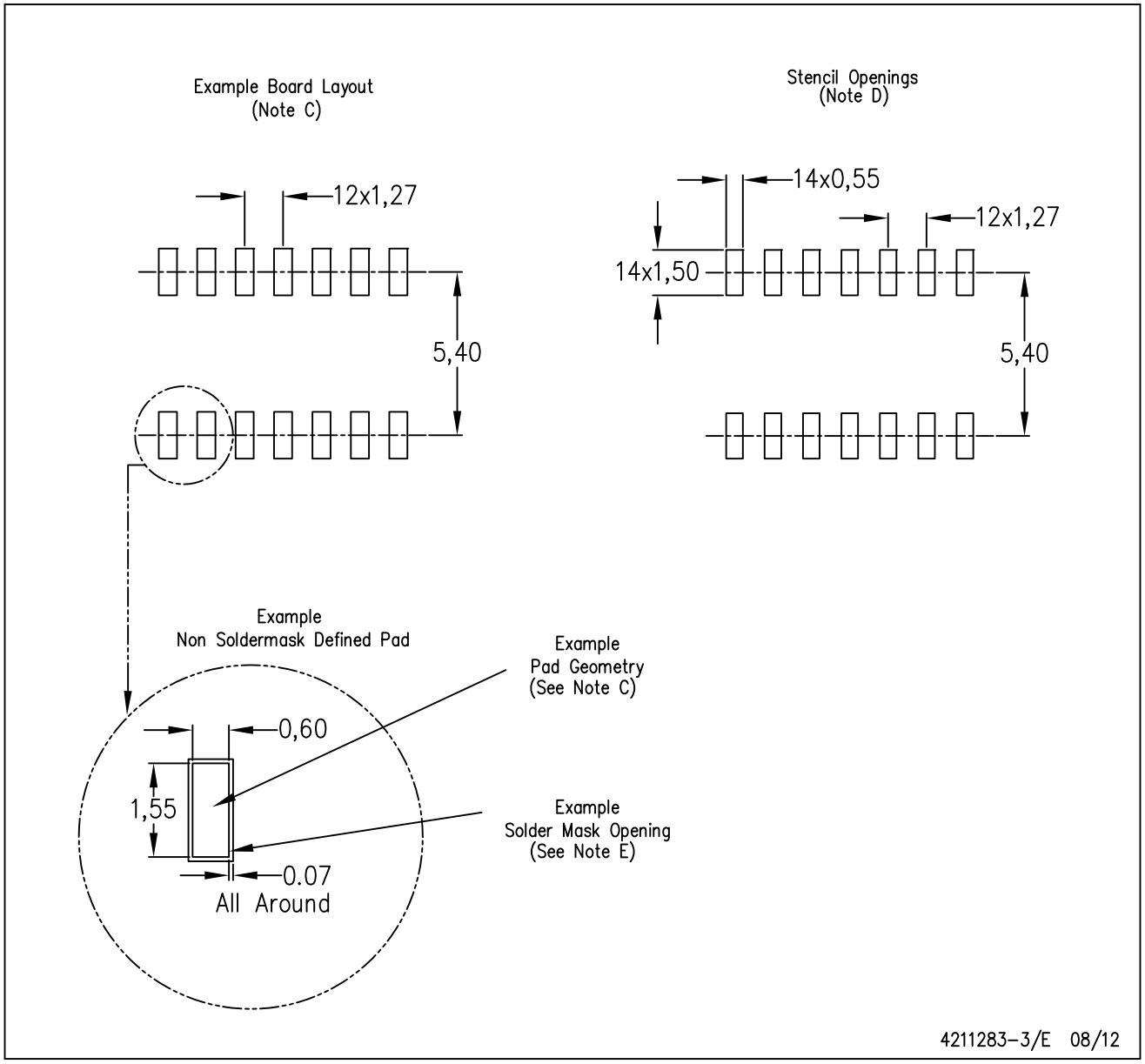
D (R–PDSO–G14) PLASTIC SMALL OUTLINE




4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE

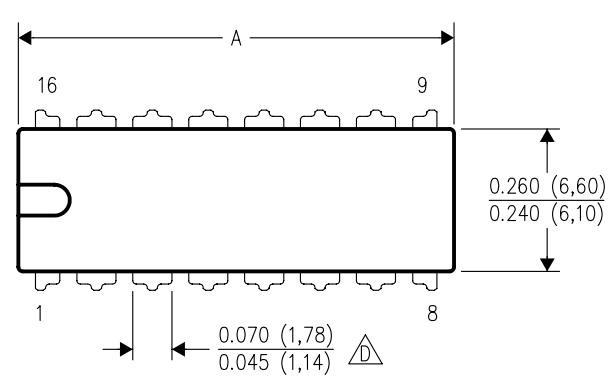



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

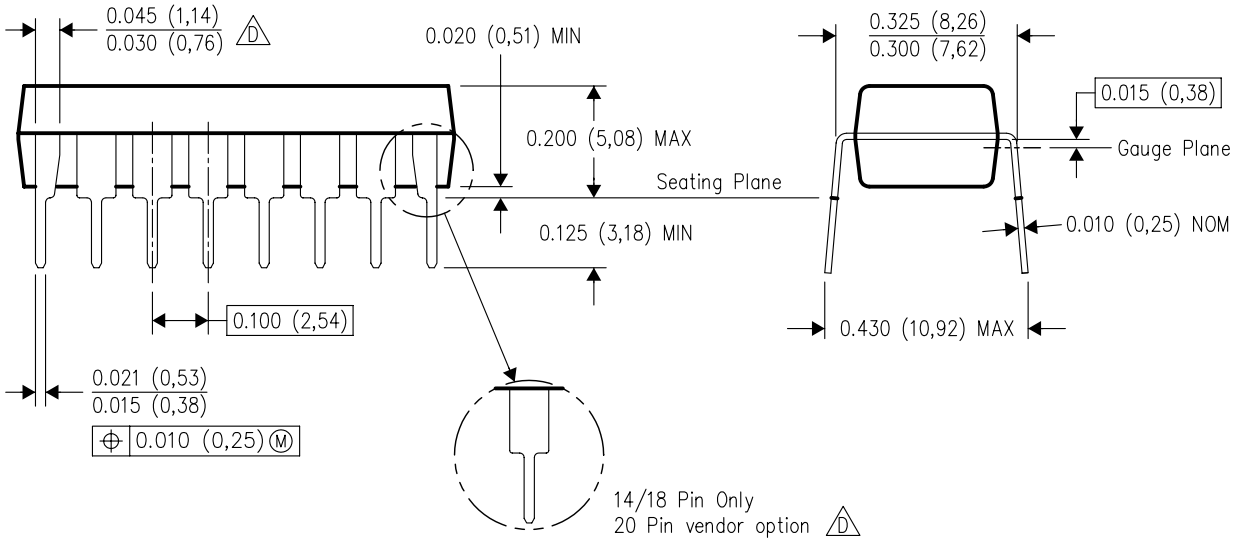
## N (R–PDIP–T**)

## PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN




| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS–001 VARIATION (C) | AA | BB | AC | AD |




4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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